64K x 18 Bit Asynchronous/ Latched Address Fast Static RAM

The MCM67A618 is a 1,179,648 bit latched address static random access memory organized as 65,536 words of 18 bits, fabricated with Motorola's high–performance silicon–gate BiCMOS technology. The device integrates a 64K x 18 SRAM core with advanced peripheral circuitry consisting of address and data input latches, active low chip enable, separate upper and lower byte write strobes, and a fast output enable. This device has increased output drive capability supported by multiple power pins.

Address, data in, and chip enable latches are provided. When latch enables (AL for address and chip enables and DL for data in) are high, the address, data in, and chip enable latches are in the transparent state. If latch enables are tied high the device can be used as an asynchronous SRAM. When latch enables are low the address, data in, and chip enable latches are in the latched state. This input latch simplifies read and write cycles by guaranteeing address and data—in hold time in a simple fashion.

Dual write enables (\overline{LW} and \overline{UW}) are provided to allow individually writeable bytes. \overline{LW} controls DQ0 – DQ8 (the lower bits) while \overline{UW} controls DQ9 – DQ17 (the upper bits).

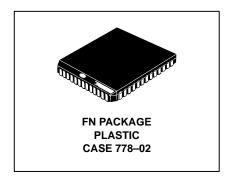
Six pair of power and ground pins have been utilized and placed on the package for maximum performance.

The MCM67A618 will be available in a 52-pin plastic leaded chip carrier (PLCC).

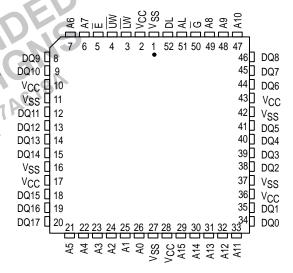
This device is ideally suited for systems that require wide data bus widths, cache memory, and tag RAMs.

- Single 5 V ± 5% Power Supply
- Fast Access Times: 10/12/15 ns Max
- Byte Writeable via Dual Write Enables
- Separate Data Input Latch for Simplified Write Cycles
- Address and Chip Enable Input Latches
- Common Data Inputs and Data Outputs
- Output Enable Controlled Three–State Outputs
- 3.3 V I/O Compatible
- · High Board Density 52-Lead PLCC Package

MCM67A618



PIN ASSIGNMENT



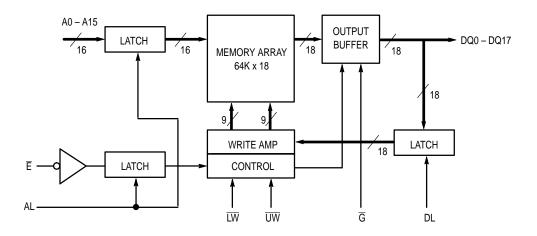
1 111 10 111120
A0 – A15 Address Inputs AL Address Latch DL Data Latch \overline{\text{LW}} Lower Byte Write Enable \overline{\text{UW}} Higher Byte Write Enable \overline{\text{E}} Chip Enable \overline{\text{G}} Output Enable \overline{\text{DQ0}} - DQ17 Data Input/Output \overline{\text{VCC}} + 5 \ V Power Supply \overline{\text{VS}} Ground

All power supply and ground pins must be connected for proper operation of the device.

REV 4 5/95



BLOCK DIAGRAM



TRUTH TABLE

Ē	LW	υw	AL*	DL*	G	Mode	Supply Current	I/O Status
Н	Х	Х	Х	Х	Х	Deselected Cycle	I _{SB}	High-Z
L	Х	Х	L	Х	Х	Read or Write Using Latched Addresses	Icc	_
L	Х	Х	Н	Х	Х	Read or Write Using Unlatched Addresses	Icc	_
L	Н	Н	Х	Х	L	Read Cycle	Icc	Data Out
L	Н	Н	Х	Х	Н	Read Cycle	Icc	High-Z
L	L	L	Х	L	Х	Write Both Bytes Using Latched Data In	ICC	High-Z
L	Ĺ	L	Х	Н	Х	Write Both Bytes Using Unlatched Data In	Icc	High–Z
L	L	Н	Х	Х	Х	Write Cycle, Lower Byte	Icc	High–Z
L	Н	L	Х	Х	Х	Write Cycle, Lower Byte	Icc	High-Z

^{*}E and Addresses satisfy the specified setup and hold times for the falling edge of AL. Data-in satisfies the specified setup and hold times for falling edge of DL.

NOTE: This truth table shows the application of each function. Combinations of these functions are valid.

ABSOLUTE MAXIMUM RATINGS (Voltages Referenced to $V_{SS} = 0$)

Rating	Symbol	Value	Unit
Power Supply Voltage	Vcc	- 0.5 to 7.0	V
Voltage Relative to V _{SS} for Any Pin Except V _{CC}	V _{in} , V _{out}	- 0.5 to V _{CC} + 0.5	V
Output Current (per I/O)	l _{out}	± 30	mA
Power Dissipation	PD	1.6	W
Temperature Under Bias	T _{bias}	- 10 to + 85	°C
Operating Temperature	T _A	0 to + 70	°C
Storage Temperature	T _{stg}	- 55 to + 125	°C

NOTE: Permanent device damage may occur if ABSOLUTE MAXIMUM RATINGS are exceeded. Functional operation should be restricted to RECOMMENDED OPER-ATING CONDITIONS. Exposure to higher than recommended voltages for extended periods of time could affect device reliability.

This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields; however, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages to this high-impedance circuit.

This BiCMOS memory circuit has been designed to meet the dc and ac specifications shown in the tables, after thermal equilibrium has been established.

This device contains circuitry that will ensure the output devices are in High–Z at power up.

DC OPERATING CONDITIONS AND CHARACTERISTICS

(V_{CC} = 5.0 V \pm 5%, T_A = 0 to + 70°C, Unless Otherwise Noted)

RECOMMENDED OPERATING CONDITIONS (Voltages referenced to $V_{SS} = 0 V$)

Parameter	Symbol	Min	Max	Unit
Supply Voltage (Operating Voltage Range)	Vcc	4.75	5.25	V
Input High Voltage	V _{IH}	2.2	V _{CC} + 0.3**	V
Input Low Voltage	V _{IL}	- 0.5*	0.8	V

DC CHARACTERISTICS

Parameter	Symbol	Min	Max	Unit
Input Leakage Current (All Inputs, V _{in} = 0 to V _{CC})	llkg(l)	_	± 1.0	μΑ
Output Leakage Current ($\overline{G} = V_{IH}$)	llkg(O)	_	± 1.0	μΑ
AC Standby Current (\overline{G} = V _{IH} , I _{Out} = 0 mA, All Inputs = V _{IL} and V _{IH} , V _{IL} = 0.0 V and V _{IH} \geq 3.0 V, Cycle Time \geq t _{AVAV} min)	ICCA10 ICCA12 ICCA15	_	290 280 265	mA
AC Standby Current (\overline{E} = V _{IH} , I _{Out} = 0 mA, All Inputs = V _{IL} and V _{IH} , V _{IL} = 0.0 V and V _{IH} \geq 3.0 V, Cycle Time \geq t _{AVAV} min)	I _{SB1}	_	95	mA
CMOS Standby Current $(\overline{E} \ge V_{CC} - 0.2$, All Inputs $\ge V_{CC} - 0.2$ V or ≤ 0.2 V, f = f _{max})	I _{SB2}	_	20	mA
Output Low Voltage (I _{OL} = + 8.0 mA)	VOL	_	0.4	V
Output High Voltage (I _{OH} = - 4.0 mA)	Voн	2.4	3.3	V

CAPACITANCE (f = 1.0 MHz, dV = 3.0 V, $T_A = 25$ °C, Periodically Sampled Rather Than 100% Tested)

Characteristic	Symbol	Тур	Max	Unit
Input Capacitance (All Pins Except DQ0 – DQ17)	C _{in}	4	5	pF
Input/Output Capacitance (DQ0 – DQ17)	C _{I/O}	6	8	pF

^{*} V_{IL} (min) = -0.5 V dc; V_{IL} (min) = -2.0 V ac (pulse width ≤ 20 ns) for $I \le 20.0$ mA.
** V_{IH} (max) = V_{CC} + 0.3 V dc; V_{IH} (max) = V_{CC} + 2.0 V ac (pulse width ≤ 20 ns) for $I \le 20.0$ mA.

AC OPERATING CONDITIONS AND CHARACTERISTICS

(V_{CC} = $5.0 \text{ V} \pm 5\%$, T_A = $0 \text{ to} + 70^{\circ}\text{C}$, Unless Otherwise Noted)

Input Timing Measurement Reference Level 1.5 V	Output Timing Reference Level
Input Pulse Levels 0 to 3.0 V	Output Load Figure 1 Unless Otherwise Noted
Input Rise/Fall Time	

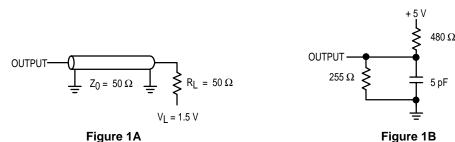
ASYNCHRONOUS READ CYCLE TIMING (See Notes 1 and 2)

		МСМ67	A618–10	MCM67	A618–12	MCM67	A618–15		
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes
Read Cycle Times	^t AVAV	10	_	12	_	15	_	ns	3
Access Times: Address Valid to Output Valid E Low to Output Valid Output Enable Low to Output Valid	^t AVQV ^t ELQV ^t GLQV	_ _ _	10 10 5	_ _ _	12 12 6	_ _ _	15 15 7	ns	4
Output Hold from Address Change	^t AXQX	4	_	4	_	4	_	ns	
Output Buffer Control: E Low to Output Active G Low to Output Active E High to Output High–Z G High to Output High–Z	[†] ELQX [†] GLQX [†] EHQZ [†] GHQZ	3 1 2 2	 5 5	3 1 2 2	 6 6	3 1 2 2	_ _ 7 7	ns	5
Power Up Time	^t ELICCA	0	_	0	_	0	_	ns	

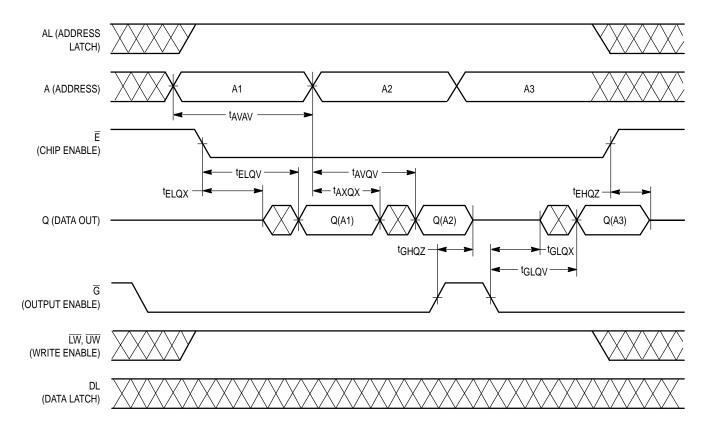
NOTES:

- 1. AL and DL are equal to $V_{\mbox{\scriptsize IH}}$ for all asynchronous cycles.
- 2. Both Write Enable signals $(\overline{LW}, \overline{UW})$ are equal to V_{IH} for all read cycles.
- 3. All read cycle timing is referenced from the last valid address to the first transitioning address.
- 4. Addresses valid prior to or coincident with $\overline{\mathsf{E}}$ going low.
- 5. Transition is measured ± 500 mV from steady–state voltage with output load of Figure 1B. This parameter is sampled and not 100% tested. At any given voltage and temperature, tehoz is less than telox and temperature, tehoz is less than telox and temperature.

AC TEST LOADS



ASYNCHRONOUS READ CYCLES



ASYNCHRONOUS WRITE CYCLE TIMING (See Notes 1, 2, and 3)

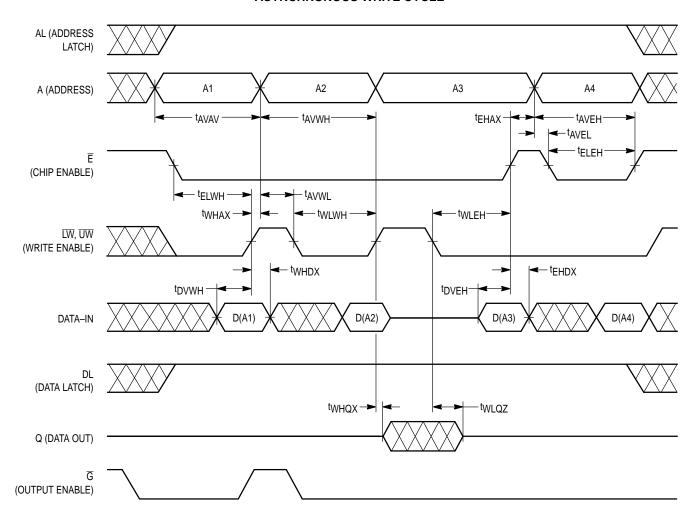
		MCM67	CM67A618-10 MCM67A618-12		MCM67A618-15				
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes
Write Cycle Times	tAVAV	10	_	12	_	15	_	ns	4
Setup Times: Address Valid to End of Writ Address Valid to E Hig Address Valid to W Lov Address Valid to E Lov Data Valid to W Hig Data Valid E Hig	tavel tavel tavel tavel tovel	9 9 0 0 5 5		10 10 0 0 6 6		13 13 0 0 7 7		ns	
Hold Times: \overline{W} High to Address Invali \overline{E} High to Address Invali \overline{W} High to Data Invali \overline{E} High to Data Invali	d tEHAX	0 0 0 0	_ _ _ _	0 0 0 0	_ _ _ _	0 0 0 0	_ _ _ _	ns	
Write Pulse Width: Write Pulse Width (G Low Write Pulse Width (G High Write Pulse Width Enable to End of Write Enable to End of Write	tWLEH tELWH	9 8 9 9	_ _ _ _ _	10 9 10 10	_ _ _ _ _	13 12 13 13 13	_ _ _ _	ns	5 6 5, 6
Output Buffer Control: $\overline{\overline{W}}$ High to Output Activ $\overline{\overline{W}}$ Low to Output High-		3 0	<u> </u>	3 0	<u> </u>	3 0	— 9	ns	7 7, 8

NOTES:

- 1. W (write) refers to either one or both byte write enables \overline{LW} and \overline{UW} .
- 2. AL and DL are equal to VIH for all asynchronous cycles.
- 3. Both Write Enables must be equal to $V_{\mbox{\scriptsize IH}}$ for all address transitions.
- 4. All write cycle timing is referenced from the last valid address to the first transitioning address.
- 5. If \overline{E} goes high coincident with or before \overline{W} goes high the output will remain in a high impedance state.
- 6. If \overline{E} goes low coincident with or after \overline{W} goes low the output will remain in a high impedance state.
- 7. Transition is measured ± 500 mV from steady–state voltage with output load of Figure 1B. This parameter is sampled and not 100% tested. At any given voltage and temperature, twLqz is less than twHqx for a given device.
- 8. If \overline{G} goes low coincident with or after \overline{W} goes low the output will remain in a high impedance state.

MCM67A618 MOTOROLA FAST SRAM

ASYNCHRONOUS WRITE CYCLE



LATCHED READ CYCLE TIMING (See Notes 1 and 2)

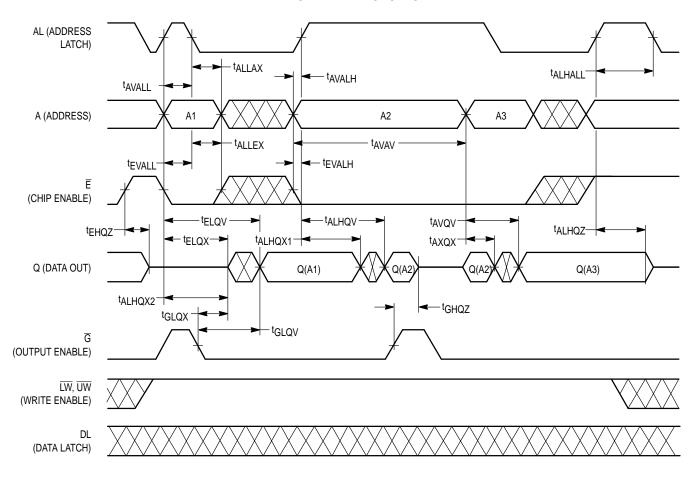
		MCM67A618-10		MCM67	A618–12	MCM67A618-15			
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes
Read Cycle Times	t _{AVAV}	10	_	12	_	15	_	ns	3
Access Times: Address Valid to Output Valid E Low to Output Valid AL High to Output Valid Output Enable Low to Output Valid	^t AVQV ^t ELQV ^t ALHQV ^t GLQV	_ _ _ _	10 10 10 5	_ _ _ _	12 12 12 6	 	15 15 15 7	ns	3 4
Setup Times: Address Valid to AL Low E Valid to AL Low Address Valid to AL High E Valid to AL High	[†] AVALL [†] EVALL [†] AVALH [†] EVALH	2 2 0 0	_ _ _ _	2 2 0 0	_ _ _ _	2 2 0 0	_ _ _ _	ns	4 4
Hold Times: AL Low to Address Invalid AL Low to E Invalid	[†] ALLAX [†] ALLEX	2 2	_	2 2	_	3 3	_	ns	4
Output Hold: Address Invalid to Output Invalid AL High to Output Invalid	[†] AXQX [†] ALHQX1	4 4	_ _	4 4	_ _	4 4	_ _	ns	
Address Latch Pulse Width	^t ALHALL	5	_	5	_	5	_	ns	
Output Buffer Control: E Low to Output Active G Low to Output Active AL High to Output Active E High to Output High–Z AL High to Output High–Z G High to Output High–Z	[†] ELQX [†] GLQX [†] ALHQX2 [†] EHQZ [†] ALHQZ [†] GHQZ	3 1 3 2 2 2		3 1 3 2 2 2		3 1 3 2 2 2	— — 9 9 7	ns	5

NOTES:

- 1. Both Write Enable Signals ($\overline{\text{LW}}, \overline{\text{UW}})$ are equal to VIH for all read cycles.
- 2. All read cycle timing is referenced from the last valid address to the first transitioning address.
- 3. Addresses valid prior to or coincident with $\overline{\mathsf{E}}$ going low.
- 4. All latched inputs must meet the specified setup and hold times with stable logic levels for ALL falling edges of address latch (AL) and data latch (DL).
- 5. Transition is measured ± 500 mV from steady–state voltage with output load of Figure 1B. This parameter is sampled and not 100% tested. At any given voltage and temperature, tehQZ is less than telQX and telQX is less than telQX and telQX for a given device.

MCM67A618 MOTOROLA FAST SRAM

LATCHED READ CYCLES



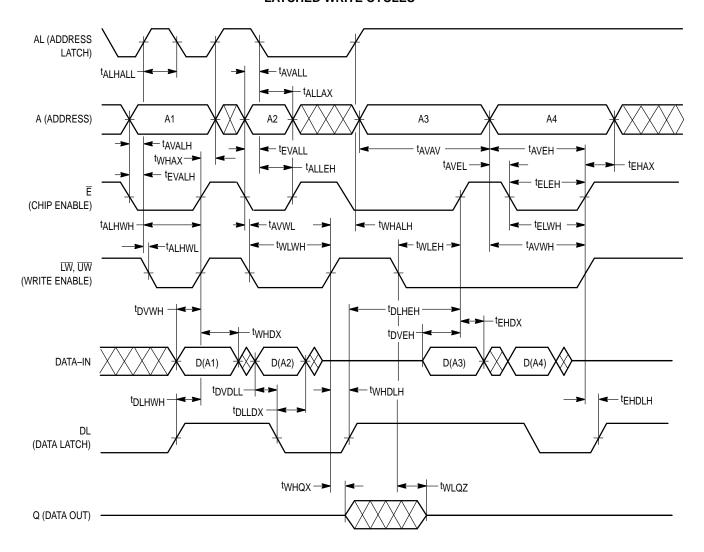
LATCHED WRITE CYCLE TIMING (See Notes 1, 2, and 3)

		MCM67	M67A618-10 MCM67A618-12		MCM67	A618–15			
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes
Write Cycle Times:	t _{AVAV}	10	_	12	_	15	_	ns	4
Address Valid to Address Valid									
Setup Times:								ns	
Address Valid to End of Write	^t AVWH	9	-	10	_	13	_		
Address Valid to End of Write	^t AVEH	9	-	10	_	13	_		
E Valid to AL Low	^t EVALL	2	–	2	_	2	_		
Address Valid to AL Low	^t AVALL	2	-	2	_	2	_		
E Valid to AL High	^t EVALH	0	-	0	_	0	_ _		
Address Valid to AL High	^t AVALH	0	-	0	l —	0	_		
AL High to $\overline{\mathbb{W}}$ Low	tALHWL	0	-	0	l —	0			
Address Valid to $\overline{\mathbb{W}}$ Low	^t AVWL	0	-	0	_	0	_		
Address Valid to \overline{E} Low	^t AVEL	0	-	0	_	0	_	ĺ	
Data Valid to DL Low	^t DVDLL	2	-	2	_	2	_		
Data Valid to $\overline{\underline{W}}$ High	^t DVWH	5	-	6	_	7	_		
Data Valid to E High	^t DVEH	5	-	6	_	7	_		
DL High to W High	^t DLHWH	5	-	6	_	7	_		
DL High to \overline{E} High	^t DLHEH	5	-	6	-	7	_		
Hold Times:								ns	
AL Low to \overline{E} High	^t ALLEH	2	l –	2	_	3	_		4
AL Low to Address Invalid	tALLAX	2	l –	2	_	3	_		4
DL Low to Data Invalid	tDLLDX	2	l –	2	_	3	_		
W High to Address Invalid	tWHAX	0	-	0	l –	0	_		
E High to Address Invalid	^t EHAX	0	-	0	_	0	_		
W High to Data Invalid	tWHDX	0	–	0	_	0	_		
E High to Data Invalid	tEHDX	0	-	0	_	0	_		
W High to DL High	tWHDLH	0	-	0	_	0	_		
E High to DL High	^t EHDLH	0	-	0	_	0	_		
$\overline{\mathbb{W}}$ High to AL High	tWHALH	0	-	0	-	0	_		
Write Pulse Width:								ns	
AL High to \overline{W} High	t _{ALHWH}	9	l –	10		13	_		5
Write Pulse Width (G Low)	tWLWH	9	l –	10	l —	13	—	ĺ	
Write Pulse Width (G High)	tWLWH	8	l –	9	l –	12	_		
Write Pulse Width	tWLEH	9	l –	10	l –	13	-		6
Enable to End of Write	tELWH	9	-	10	-	13	_	ĺ	7
Enable to End of Write	^t ELEH	9	-	10	-	13	_		6, 7
Address Latch Pulse Width	^t ALHALL	5	_	5	<u> </u>	5	_	ns	4
Output Buffer Control:								ns	
W High to Output Active	tWHQX	3	l –	3	l –	3	l —		8
W Low to Output High-Z	tWLQZ	0	5	0	6	0	9		8, 9

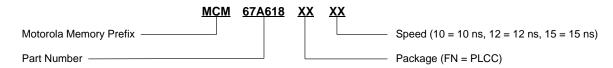
NOTES:

- 1. \overline{W} refers to either one or both byte write enables \overline{LW} and \overline{UW} .
- 2. A write occurs during the overlap of \overline{E} low and \overline{W} low.
- 3. Both Write Enables must be equal to $V_{\mbox{\scriptsize IH}}$ for all address transitions.
- 4. All write cycle timing is referenced from the last valid address to the first transitioning address.
- 5. All latched inputs must meet the specified setup and hold times with stable logic levels for ALL falling edges of address latch (AL) and data latch (DL).
- 6. If \overline{E} goes high coincident with or before \overline{W} goes high the output will remain in a high impedance state.
- 7. If \overline{E} goes low coincident with or after \overline{W} goes low the output will remain in a high impedance state.
- 8. Transition is measured \pm 500 mV from steady–state voltage with output load of Figure 1B. This parameter is sampled and not 100% tested. At any given voltage and temperature, t_{WLQZ} is less than t_{WHQX} for a given device.
- 9. If \overline{G} goes low coincident with or after \overline{W} goes low the output will remain in a high impedance state.

LATCHED WRITE CYCLES



ORDERING INFORMATION (Order by Full Part Number)

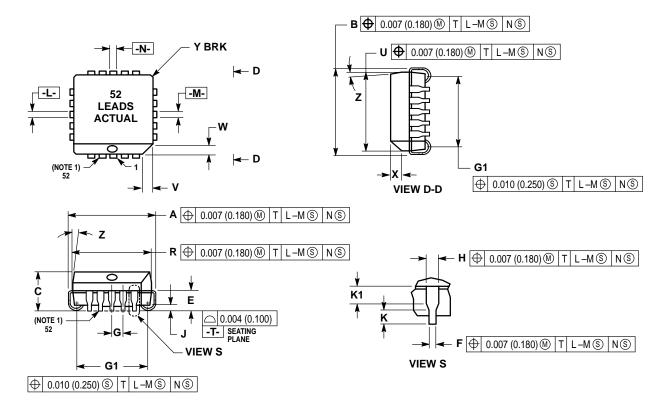


Full Part Numbers — MCM67A618FN10 MCM67A618FN12 MCM67A618FN15

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PACKAGE DIMENSIONS

FN PACKAGE 52-LEAD PLCC **CASE 778-02**



NOTES

1982

- DUE TO SPACE LIMITATION, CASE 778-02 SHALL BE REPRESENTED BY A GENERAL (SMALLER) CASE OUTLINE DRAWING RATHER THAN SHOWING ALL 52 LEADS.
 DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF
- LEAD SHOULDER EXITS PLASTIC BODY AT MOLD
- PARTING LINE.

 DIM 61, TRUE POSITION TO BE MEASURED AT DATUM -T-,
 SEATING PLANE.

 DIM R AND U DO NOT INCLUDE MOLD FLASH.
- ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE DIMENSIONING AND TOLERANCING PER ANSI Y14.5M,
- CONTROLLING DIMENSION: INCH.
- THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE
- PLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.

 DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INC	HES	MILLIN	METERS
DIM	MIN	MAX	MIN	MAX
Α	0.785	0.795	19.94	20.19
В	0.785	0.795	19.94	20.19
С	0.165	0.180	4.20	4.57
Е	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.05	0 BSC	1.27	BSC
Н	0.026	0.032	0.66	0.81
J	0.020	_	0.51	_
K	0.025	_	0.64	_
R	0.750	0.756	19.05	19.20
U	0.750	0.756	19.05	19.20
٧	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
Х	0.042	0.056	1.07	1.42
Υ	_	0.020		0.50
Z	2°	10°	2°	10°
G1	0.710	0.730	18.04	18.54
K1	0.040	_	1.02	_

Literature Distribution Centers:

USA/EUROPE: Motorola Literature Distribution; P.O. Box 20912; Phoenix, Arizona 85036. JAPAN: Nippon Motorola Ltd.; 4-32-1, Nishi-Gotanda, Shinagawa-ku, Tokyo 141, Japan.

ASIA PACIFIC: Motorola Semiconductors H.K. Ltd.; Silicon Harbour Center, No. 2 Dai King Street, Tai Po Industrial Estate, Tai Po, N.T., Hong Kong.



